

STTH30W02C

Turbo 2 ultrafast high voltage rectifier

Datasheet - production data

Features

- Ultrafast switching
- Low reverse recovery current
- Low thermal resistance
- Reduces switching losses
- ECOPACK[®]2 compliant component

Description

The STTH30W02CW, uses ST Turbo 2, 200 V technology. It is especially suited to be used for DC/DC and DC/AC converters in secondary stage of MIG/MMA/TIG welding machine. Housed in ST's TO-247, this device offers high power integration for all welding machines and industrial applications.

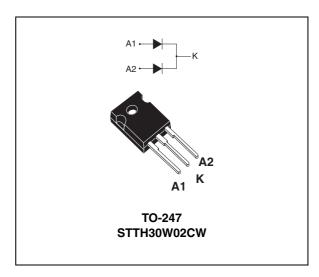


Table 1. Device summary

| Symbol | Value |
|-----------------------|----------|
| I _{F(AV)} | 2 x 15 A |
| V _{RRM} | 200 V |
| t _{rr} (typ) | 20 ns |
| T _i (max) | 175 °C |
| V _F (typ) | 0.90 V |

Characteristics STTH30W02C

1 Characteristics

Table 2. Absolute ratings (limiting values, at 25 °C, unless otherwise specified)

| Symbol | Paramete | Value | Unit | | | |
|---------------------|---|-------------------------|------------|-----|---|--|
| V_{RRM} | Repetitive peak reverse voltage | | | 200 | V | |
| I _{F(RMS)} | Forward rms current | | | 30 | Α | |
| I _{F(AV)} | Average forward current, $\delta = 0.5$ | T _c = 125 °C | Per diode | 15 | А | |
| | | T _c = 115°C | Per device | 30 | | |
| I _{FSM} | Surge non repetitive forward current $t_p = 10 \text{ ms sinusoidal}$ | | | 140 | Α | |
| T _{stg} | Storage temperature range | -65 to + 175 | °C | | | |
| T _j | Maximum operating junction tempera | + 175 | °C | | | |

Table 3. Thermal resistance

| Symbol | Parameter | Value | Unit | |
|----------------------|------------------|-----------|------|--------|
| В | Junction to case | Per diode | 2.5 | |
| R _{th(j-c)} | Total | Total | 1.5 | °C / W |
| R _{th(c)} | Coupling | | 0.5 | |

When diodes 1 and 2 are used simultaneously:

 $T_{j}(diode 1) = P(diode 1) \times R_{th(j-c)}(per diode) + P(diode 2) \times R_{th(c)}$

Table 4. Static electrical characteristics

| Symbol | Parameter | Test conditions | | Min. | Тур | Max. | Unit |
|--|---------------------------|-------------------------|-----------------------------------|------|------|------|------|
| I _R ⁽¹⁾ Reverse leak | Deverage legicoge gurrent | T _j = 25 °C | V _R = V _{RRM} | | | 10 | μΑ |
| | neverse leakage current | T _j = 125 °C | | | 5 | 50 | |
| | | T _j = 25 °C | 1. 15 \ | | | 1.20 | |
| V _F ⁽²⁾ Forward voltage drop | T _j = 150 °C | I _F = 15A | | 0.90 | 1.05 | V | |
| | Forward voltage drop | T _j = 25 °C | 1 20 A | | | 1.4 | V |
| | | T _j = 150 °C | I _F = 30 A | | 1.1 | 1.3 | |

^{1.} Pulse test: $t_p = 5$ ms, $\delta < 2\%$

To evaluate the conduction losses use the following equation:

$$P = 0.8 \text{ x } I_{F(AV)} + 0.0167 I_{F(RMS)}^{2}$$

^{2.} Pulse test: t_p = 380 μ s, δ < 2%

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Table 5. Dynamic electrical characteristics

| Symbol | Parameter | Test conditions | | | Тур | Max. | Unit |
|---------------------|--------------------------|--|---|--|-----|------|------|
| I _{RM} | Reverse recovery current | | 15 4 1/ 100 1/ | | 7 | 9 | Α |
| Q _{RR} | Reverse recovery charge | T _j = 125 °C | $I_F = 15 \text{ A}, V_R = 160 \text{ V}$ $dI_F/dt = -200 \text{ A/}\mu\text{s}$ | | 160 | | nC |
| S _{factor} | Softness factor | | | | 0.3 | | |
| t _{rr} | Reverse recovery time | T _j = 25 °C | $I_F = 1 \text{ A}, V_R = 30 \text{ V}$ $dI_F/dt = -100 \text{ A/}\mu\text{s}$ | | 20 | 25 | ns |
| t _{fr} | Forward recovery time | $T_j = 25 ^{\circ}\text{C}$ $I_F = 15 \text{A}, V_{FR} = 1.1 \text{V}$ | | | | 200 | ns |
| V _{FP} | Forward recovery voltage | T _j = 25 °C | dI _F /dt = 100 A/μs | | 1.6 | 2.4 | V |

Figure 1. Average forward power dissipation Figure 2. Forward voltage drop versus versus average forward current (per diode) forward current (per diode)

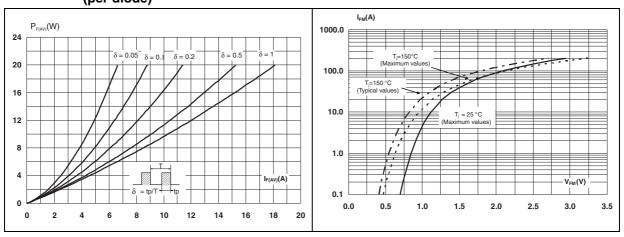


Figure 4.

Figure 3. Relative variation of thermal impedance junction to case versus pulse duration

Peak reverse recovery current

versus dl_F/dt (typical values, per

 $Z_{th(j-c)}/R_{th(j-c)}$ 1.0 0.9 0.8 0.7 0.6 0.5 0.4 0.3 0.2 0.1 0.0 1.E-04 1.E-03 1.E-02 1.E-01 1.E+00

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Figure 5. Reverse recovery time versus dl_F/dt Figure 6. Reverse recovery charges versus (typical values, per diode) dl_F/dt (typical values, per diode)

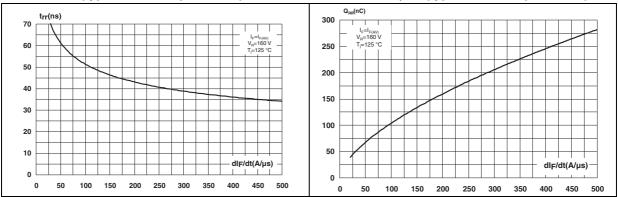


Figure 7. Relative variations of dynamic parameters versus junction temperature

Figure 8. Reverse recovery softness factor versus dl_F/dt (typical values, per diode)

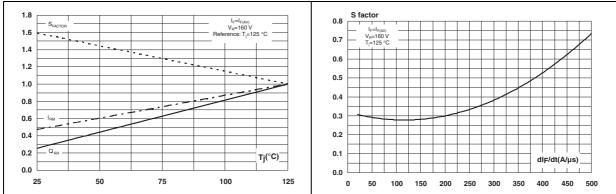
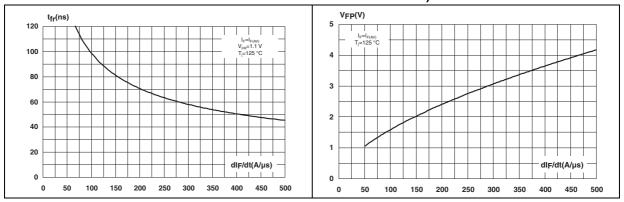


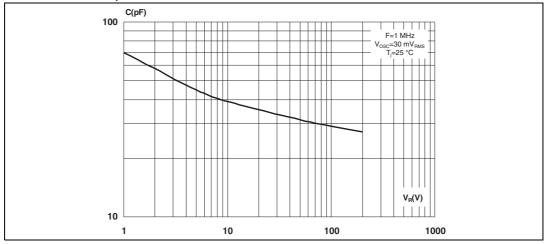
Figure 9. Forward recovery time versus dl_F/dt Figure 10. Transient peak forward voltage (typical values, per diode)

Transient peak forward voltage versus dl_F/dt (typical values, per diode)



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Figure 11. Junction capacitance versus reverse voltage applied (typical values, per diode)



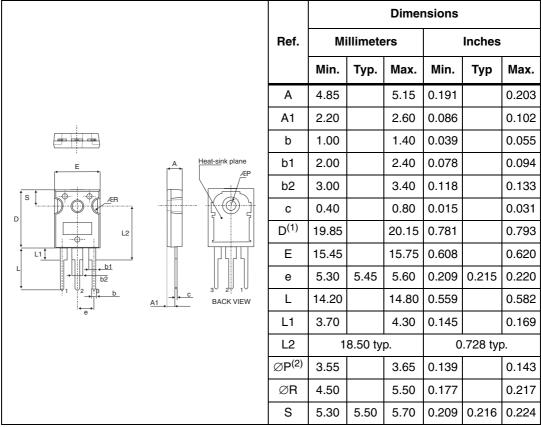
Package information STTH30W02C

2 Package information

- Epoxy meets UL94, V0
- Cooling method: by conduction (C)
- Recommended torque value: 0.55 N·m (1.0 N·m maximum)

In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK[®] packages, depending on their level of environmental compliance. ECOPACK[®] specifications, grade definitions and product status are available at: www.st.com. ECOPACK[®] is an ST trademark.

Table 6. TO-247 dimensions



- 1. Dimension D plus gate protrusion does not exceed 20.5 mm
- 2. Resin thickness around the mounting hole is not less than 0.9 mm

3 Ordering information

Table 7. Ordering information

| Ordering type | Marking | Package | Weight | Base qty | Delivery mode |
|---------------|-------------|---------|--------|----------|---------------|
| STTH30W02CW | STTH30W02CW | TO-247 | 4.46 g | 50 | Tube |

4 Revision history

Table 8. Document revision history

| Date | Revision | Changes |
|-------------|----------|--------------|
| 05-Oct-2012 | 1 | First issue. |

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